

Judul:

Lead free solder: mechanics and reliability

Pengarang/Penulis:

Pang, John Hock Lye, author

Subjek:

Solder and soldering; Lead-free electronics manufacturing processes;
Green electronics

Nomor Panggil:

e20418456

Penerbitan:

Springer

Link Terkait:

- [Deskripsi Bibliografi](#)
- [Abstrak](#)
- [Dokumen Yang Mirip](#)
- [Universitas Indonesia Library](#)